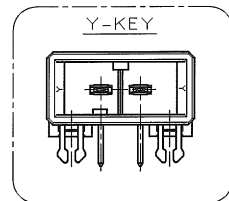
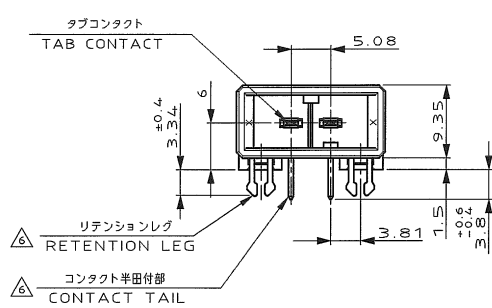
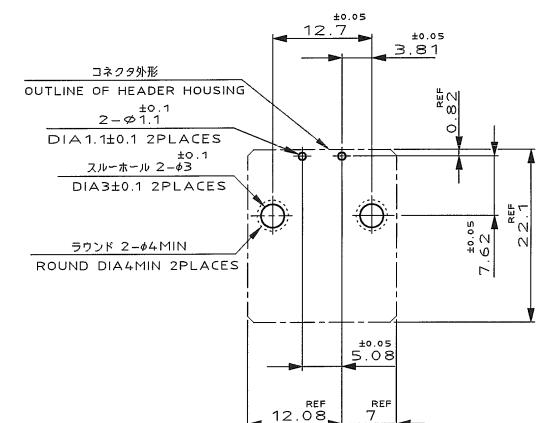
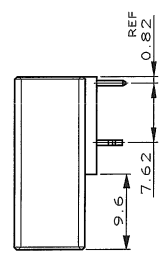
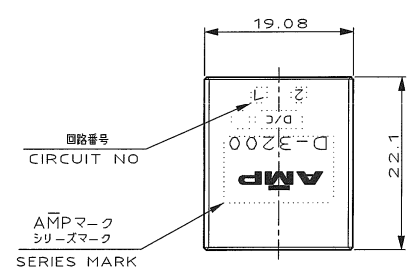


NUMBER 179276  
 3rd ANGLE PROJECTION  
 METRIC  
 DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT  
 PRINT DIST



推奨基板取付け寸法  
 PC 基板厚: 1.6±0.1  
 (非累積公差)  
 (コネクタ搭載面)

RECOMEND PC BOARD HOLE PATTERN  
 PC BOARD THICKNESS: 1.6±0.1  
 (NOT ACCUMULATE TOLERANCE)  
 (CONNECTOR MOUNT SIDE)

NOTES

- MATERIAL: HOUSING: GLASS FILLED THERMO PLASTIC, POLYESTER  
 CONTACT: COPPER ALLOY  
 RETENTION LEG: COPPER ALLOY
- FINISH (CONTACT AREA): 0.38 μm MIN GOLD PLATING OVER NI PLATING
- FINISH (CONTACT AREA): 0.76 μm MIN GOLD PLATING OVER NI PLATING
- FINISH (CONTACT AREA): 2.0 μm MIN TIN PLATED OVER NICKEL
- FINISH (RETENTION LEG): TIN LEAD PLATED (CONTACT TAIL) OVER NICKEL
- FINISH (RETENTION LEG): TIN PLATED (CONTACT TAIL) OVER NICKEL
- OBsolete PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINIS

注記

- 材料: ハウジング: ガラス入り熱可塑性ポリエチル樹脂  
 コネクタ: 銅合金  
 リテンションレグ: 銅合金
- めっき: コネクタ: 全面Ni下地  
 接触部: 0.38 μm MIN めっき
- めっき: コネクタ: 全面Ni下地  
 接触部: 0.76 μm MIN めっき
- めっき: コネクタ: 全面Ni下地  
 接触部: 2.0 μm MIN スズめっき
- めっき: リテンションレグとコンタクト半田付部  
 ニッケル下地の土は半田めっき

△	OBsolete	△	△	2-179276-5	Y
		△	△	2-179276-3	Y
		△	△	2-179276-2	Y
		△	△	1-179276-5	X
		△	△	1-179276-3	X
△	△	1-179276-2	X		
	(FINISH)	製品番号 (PART NO.)	KEY		

B2	REVISED PER ECO-11-005030	RK	HMR	22MAR11
LTR	REVISION RECORD	DR	CHK	DATE

WIRE RANGE		INSULATION DIA	NAME
mm(TAWG)		mmφ	2 POS SINGLE ROW HORIZONTAL HDR ASSY FOR DYNAMIC D-3200
MATERIAL	SEE NOTE	FINISH	SEE NOTE
DR. 1 DEC 93		DE. 1 DEC 93	
CHK. S. MANGBE		APP. S. MANGBE	
(GENERAL TOLERANCE)	SIZE	LOC	NUMBER
100% ±0.2	A3	J	C=179276
200% ±0.3	SCALE	REV.	SHEET
300% ±0.4	2-1	B2	1 OF 1

(CUSTOMER DRAWING) 顧客用図面